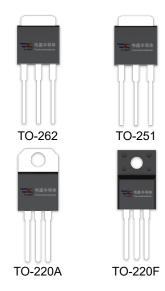
Shenzhen VSEEI Semiconductor Co., Ltd

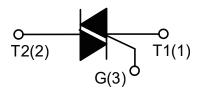
DESCRIPTION:

With high ability to withstand the shock loading of large current, T435-600W series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



MAIN FEATURES

Symbol	Value	Unit
V _{DRM} /V _{RRM}	600/800	V
I _{T(RMS)}	4	A



ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T _{stg}	-40 - 150	$^{\circ}$ C
Operating junction temperature range		Tj	-40 - 125	$^{\circ}$
Repetitive peak off-state voltage (T _j =25℃)		V _{DRM}	600/800	V
Repetitive peak reverse voltage (T _j =25℃)		V _{RRM}	600/800	V
RMS on-state current	TO-251/ TO-220A(Ins)/ TO-220F(Ins) (Tc=100℃) TO-220A(Non-Ins)/ TO-262 (Tc=105℃)	It(RMS)	4	А
Non repetitive surge peak on-state current (full cycle, F=50Hz)		I _{TSM}	40	Α
I ² t value for fusing (tp=10ms)		l ² t	8	A ² s



Critical rate of rise of on-state current $(I_G = 2 \times I_{GT})$	dl/dt	50	A/µs
Peak gate current	I _{GM}	4	Α
Average gate power dissipation	P _{G(AV)}	1	W
Peak gate power	P _{GM}	5	W

ELECTRICAL CHARACTERISTICS (T_j =25 $^{\circ}$ C unless otherwise specified)

Symbol	Test Condition	Quadrant		Value			Unit	
	rest Condition			TW	sw	CW	BW	Offic
lgт	V _D =12V R _L =33Ω	I - II -III	MAX	5	10	35	50	mA
V _G T		I - II -III	MAX	1.5				V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2			V	
IL	I _G =1.2I _{GT}	I -III	MAX	10	20	50	70	mA
		II	IVIAA	15	35	60	80	IIIA
Ін	I _T =100mA		MAX	10	15	35	60	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125 °C		MIN	50	100	400	1000	V/µs

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V _{TM}	I _{тм} =5.5A tp=380µs	T _j =25℃	1.5	V
IDRM	V _D =V _{DRM} V _R =V _{RRM}	T _j =25℃	10	μA
I _{RRM}		T _j =125℃	0.75	mA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th(j-c)}	junction to case(AC)	TO-251	2.8	°C/W
		TO-220A(Ins)	3.0	
		TO-262/ TO-220A(Non-Ins)	2.5	
		TO-220F(Ins)	3.3	



FIG.1: Maximum power dissipation versus RMS on-state current

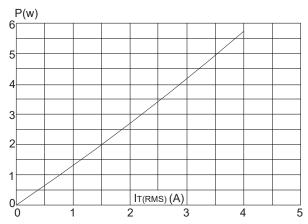


FIG.3: Surge peak on-state current versus number of cycles

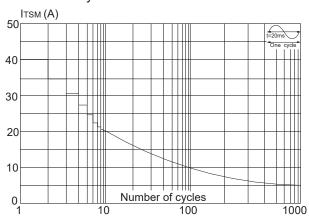


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms and corresponding value of I²t (dI/dt < 50A/µs)

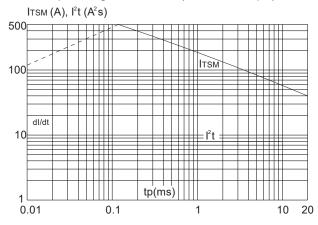


FIG.2: RMS on-state current versus case temperature

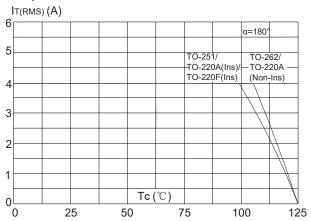


FIG.4: On-state characteristics (maximum values)

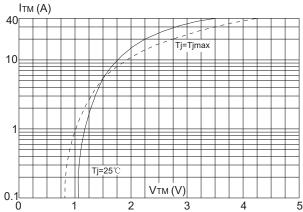


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

